PART NO. : TG110-ESV01N6LF

16PIN FAST ETHERNET ISOLATION MODULE

Pb-FREE/RoHS COMPLIANT

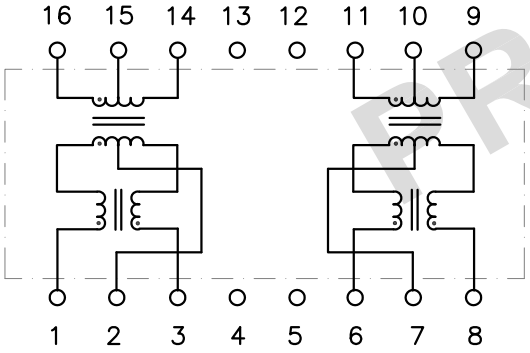
COMPATIBLE TO LEAD-FREE SOLDERING PROCESS CONDITION PER IPC/JEDEC J-STD-020C

UL/EU60950 AND DEMKO RECOGNIZED

ENHANCED SHOCK/VIBRATION PERFORMANCE

EXTENDED OPERATING TEMPERATURE -40/+85°C

STORAGE TEMPERATURE -57/+125°C



ELECTRICAL SPECIFICATIONS @25° C

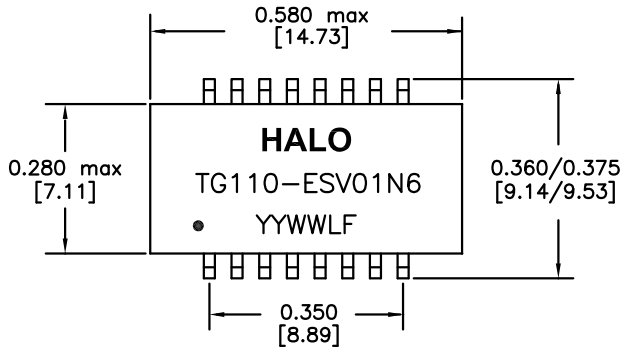
TURNS RATIO	
P1-3:P16-14	1CT:1CT ±3%
P6-8:P11-9	1CT:1CT ±3%
OCL (100KHz,0.1Vrms,8mA)	
P16-14,P11-9	350µH min*
DCR P16-14,P11-9	1.0Ω max
LL P16-14,P11-9	0.4µH max
Cw/w	40pF max
INSERTION LOSS	
0.1-100MHz	-1.1dB max
RETURN LOSS	
0.5-30MHz	-18dB min
40MHz	-15.5dB min
50MHz	-13.6dB min
60-80MHz	-12dB min
TYPICAL CROSSTALK	
0.1-100MHz	-40dB min
TYPICAL CMR	
0.1-30MHz	-60dB min
40-100MHz	-50dB min
ISOLATION	1,500Vrms

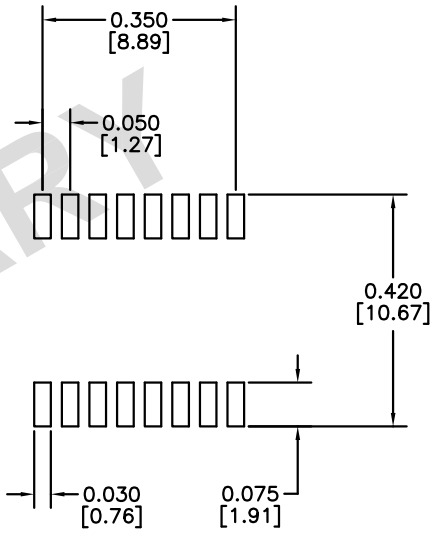
* MINIMUM OCL OVER OPERATING TEMPERATURE

HALO/PBL	TITLE	ISOLATION MODULE	SIGNATURES		DATE	REV.	DESC.	DATE
	FOR	FAST ETHERNET	DRAWN	LI ZHI ZHONG	8/31/11	A	FIRST ISSUE	8/31/11
	PART NO.	TG110-ESV01N6LF	CHECKED	LEI KEONG	8/31/11			
	SCALE	NONE	APPROVED	PETER LU	8/31/11			
	PAGE	1 OF 2	FILE	ESV01N6LF.DWG				

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

US PATENT NO. 5,656,985 6,297,720B1 6,297,721B1
6,320,489B1 6,344,785B1 6,662,431B1





CO-PLANARITY: 0.004 [0.10]
DIMENSIONS: Inch [mm]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED

RECOMMANDED SOLDER PAD DIMENSIONS

HALO/PBL	TITLE	ISOLATION MODULE	SIGNATURES		DATE	REV.	DESC.	DATE
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